

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/12/2022

Details for "CY74FCT2573CTS0CT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
CY74FCT2573CTS0CT	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	DW 20	7.52x12.82x2.35	564.9

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000001	0.000562	6	0	0
Precious Metals	Gold	7440-57-5	0.177799	99.998313	999983	0.031477	315
Precious Metals	Silver	7440-22-4	0.000002	0.001125	11	0	0
Sub-Total			0.177802	100	1000000	0.031478	315
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.257463	70.000054	700001	0.045581	456
Thermoplastics	Epoxy	85954-11-6	0.110341	29.999946	299999	0.019535	195
Sub-Total			0.367804	100	1000000	0.065115	651
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	145.72536	97.41	974100	25.798871	257989
Copper and Its Alloys	Iron	7439-89-6	3.5904	2.4	24000	0.635636	6356
Copper and Its Alloys	Phosphorus	7723-14-0	0.04488	0.03	300	0.007945	79
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.04488	0.03	300	0.007945	79
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.04488	0.03	300	0.007945	79
Zinc and Its Alloys	Zinc	7440-66-6	0.1496	0.1	1000	0.026485	265
Sub-Total			149.6	100	1000000	26.484828	264848
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	2.561582	95.120015	951200	0.453496	4535
Precious Metals	Gold	7440-57-5	0.021005	0.779985	7800	0.003719	37
Precious Metals	Palladium	7440-05-3	0.110413	4.1	41000	0.019547	195
Sub-Total			2.693	100	1000000	0.476762	4768
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	311.972416	76	760000	55.230854	552309
Other Organic Materials	Proprietary Non Halide Flame Retardant	Trade Secret	14.367151	3.5	35000	2.543526	25435
Other Plastics and Rubber	Carbon Black	1333-86-4	1.23147	0.3	3000	0.218017	2180
Thermoplastics	Epoxy	85954-11-6	82.918984	20.2	202000	14.67978	146798
Sub-Total			410.490021	100	1000000	72.672177	726722
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.523066	100	1000000	0.26964	2696
Sub-Total			1.523066	100	1000000	0.26964	2696
Total			564.851693			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
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[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1.000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1.000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.